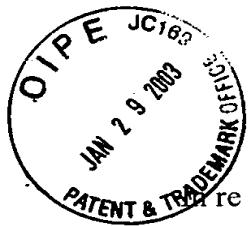


PATENT APPLICATION



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re the Application of

Hideyuki KURITA et al.

Application No.: 09/688,181

Filed: October 16, 2000

For: MULTILAYER FLEXIBLE WIRING BOARDS AND PROCESSES FOR
MANUFACTURING MULTILAYER FLEXIBLE WIRING BOARDS

Group Art Unit: 2825

Examiner: G. Lee

Docket No.: 107594

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AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed August 29, 2002, the period for reply being extended by the attached Petition for Extension of Time to January 29, 2003, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claim 16 without prejudice to or disclaimer of the subject matter contained therein.

Please replace claims 2, 3, 10 and 12 as follows:

2. (Twice Amended) A process for manufacturing a multiplayer flexible wiring board by bonding metal wirings of at least two flexible wiring board pieces having a base film including a resin film and a metal wiring provided on said base film, comprising the steps of:

a) placing said metal wirings of said two flexible wiring board pieces in close contact with each other at their surfaces,